Display Future Ltd
www.displayfuture.com

LCD MODULE SPECIFICATION

Model: DF-TFN0319FB-F1

This module uses ROHS materials

For customer acceptance

Customer		date
Approved		
Comments		

The standard product specification may change without prior notice in order to improve performance or quality. Please contact Display Future Ltd for updated specification and product status before design for the standard product or release of the order.	Revision	2.0
	Engineering	
	Date	2018/01/4
	Our Reference	

Revision record

REV NO.	REV DATE	CONTENTS	Note
A	**2012-06-18**	**NEW ISSUE**	
B	**2015-06-18**	**Modify the POL,INSPECTION**	

1. General Description

1.1 Description

DF-TFN0319FB-F1 is a Transmissive type colour active matrix liquid crystal display (LCD), which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT LCD panel, driver IC, FPC and backlight unit .
The following table described the features of DF-TFN0319FB-F1.

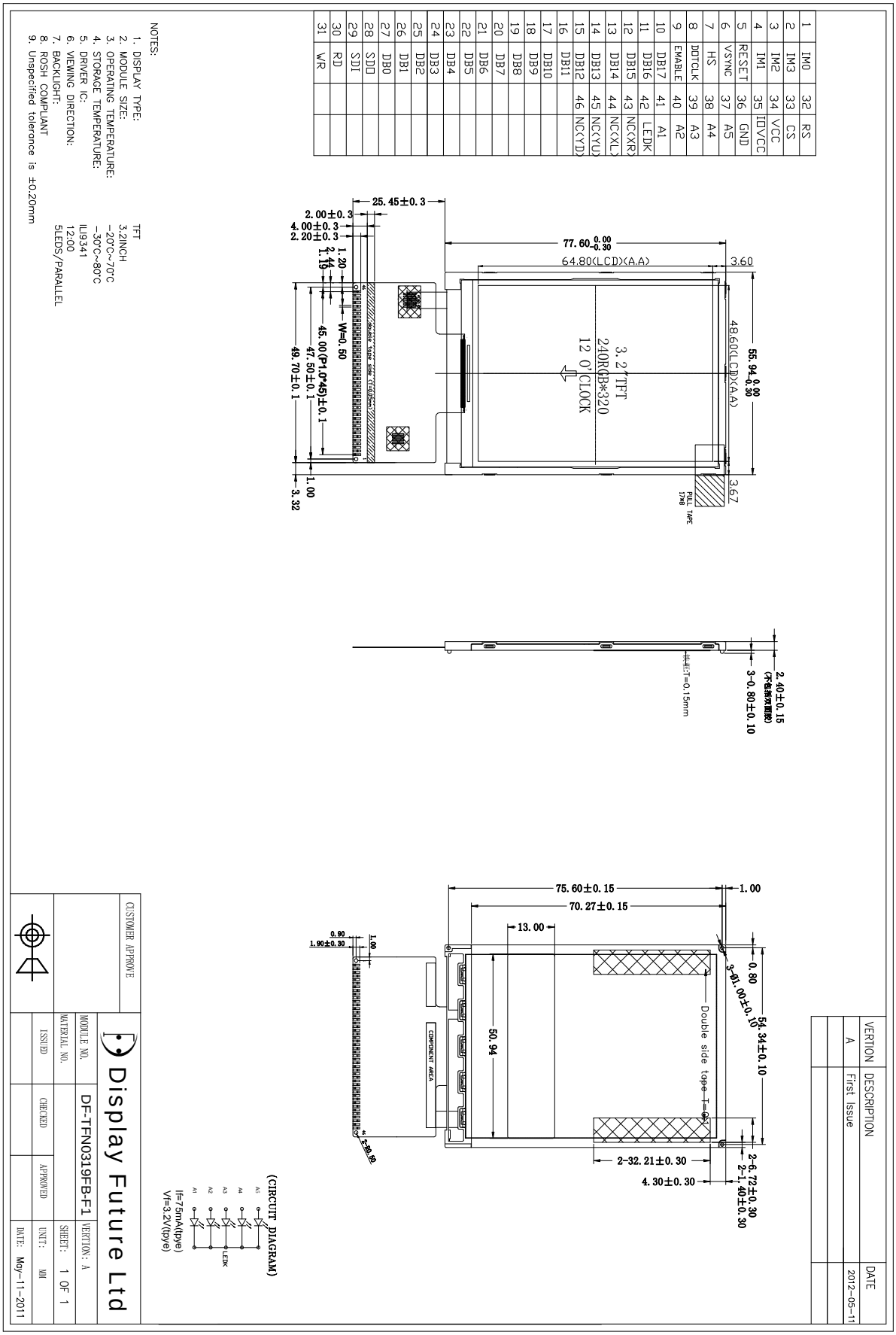
1.2 Application

Mobile phone, Multimedia products
and other electronic Products
Etc.

1.3 Features:

Features	Description	UNITS
LCD type	3.2'TFT	--
Dot arrangement	240（RGB）×320	dots
Driver IC	ILI9341	--
Color Depth	65K/262K	
Interface	RGB, Serial and MCU Interface	
View Direction	12 O'clock	
Module size	55.94(W) ×77.60 (H)×2.4(T)	mm
Active area	48.60(W) ×64.80 (H)	mm
Dot pitch	0.2025 (W) ×0.2025 (H)	mm
Back Light	5 White LED In parallel	--
With/Without TSP	Without TSP	
Weight(g)	TBD	

2. External Dimensions



1	IM0	32	RS
2	IM3	33	CS
3	IM2	34	VCC
4	IM1	35	IOVCC
5	RESET	36	GND
6	VSYNC	37	A5
7	HS	38	A4
8	DOTCLK	39	A3
9	EMABLE	40	A2
10	DB17	41	A1
11	DB16	42	LEDK
12	DB15	43	NCXR
13	DB14	44	NCXL
14	DB13	45	NCYU
15	DB12	46	NCYD
16	DB11		
17	DB10		
18	DB9		
19	DB8		
20	DB7		
21	DB6		
22	DB5		
23	DB4		
24	DB3		
25	DB2		
26	DB1		
27	DB0		
28	SDO		
29	SDI		
30	RD		
31	WR		

3. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1	IM0	The selection of the given interfaces are done by external IM[3:0] Pins and shown as below Note 1.
2	IM3	
3	IM2	
4	IM1	
5	RESET	This signal will reset the device and must be applied to properly initialize the chip. Signal is active low.
6	VSYNC	Frame synchronizing signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
7	HSYNC	Line synchronizing signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
8	DOTCLK	Dot clock signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
9	ENABLE	Data enable signal for RGB interface operation. Fix to IOVCC or GND level when not in use.
10-27	DB17-DB0	18-Bit parallel data bus for MCU system and RGB interface mode. Fix to GND level when not in use.
28	SDO	Serial output signal. The data is outputted on the falling edge of the SCL signal. If not used, open this pin.
29	SDI	The data is applied on the rising edge of the SCL signal. Fix to IOVCC or GND level when not in use.
30	RD	8080-I/8080-II system(RD):Serves as a read signal and MCU read data at the rising edge. Fix to IOVCC level when not in use.
31	WR	8080-I/8080-II system(WR):Serves as a write signal and writes data at the rising edge. 4-Line system(RS):Serves as command or parameter select. Fix to IOVCC level when not in use.
32	RS	This pin is used to select ”data or command” in the parallel interface or 4-wire 8-bit serial data interface. When RS=”1”, data is selected. When RS=”0”, command is selected. This pin is used serial interface clock in 3-wire 9-bit/4-wire 8-bit serial data interface. Fix to IOVCC or GND level when not in use.
33	CS	Chip select input pin(“ low” enable).
34	VCC	Power supply Voltage for I/O Interface (+1.65V~+2.8V).
35	IOVCC	System Power supply Voltage (+2.5V~+3.3V).
36	GND	System ground.
37	A5	Power supply for LED backlight Anode input.
38	A4	Power supply for LED backlight Anode input.
39	A3	Power supply for LED backlight Anode input.
40	A2	Power supply for LED backlight Anode input.

41	A1	Power supply for LED backlight Anode input.
42	K	Power supply for LED backlight Cathode input.
43	NC(XR)	NC(Touch Panel Right Side Wire).
44	NC(XL)	NC(Touch Panel Left Side Wire).
45	NC(YU)	NC(Touch Panel Up Side Wire).
46	NC(YD)	NC(Touch Panel Down Side Wire).

Note 1:

ILI9341 provides four kinds of MCU system interface with 8080-Ⅰ/8080-Ⅱ series parallel interface and 3-/4-line serial interface. The selection of the given interfaces are done by external IM [3:0] pins and shown as below:

IM3	IM2	IM1	IM0	MCU-Interface Mode	Pins in use	
					Register/Content	GRAM
0	0	0	0	8080 MCU 8-bit bus interface Ⅰ	D[7:0]	D[7:0],WRX,RDX,CSX,D/CX
0	0	0	1	8080 MCU 16-bit bus interface Ⅰ	D[7:0]	D[15:0],WRX,RDX,CSX,D/CX
0	0	1	0	8080 MCU 9-bit bus interface Ⅰ	D[7:0]	D[8:0],WRX,RDX,CSX,D/CX
0	0	1	1	8080 MCU 18-bit bus interface Ⅰ	D[7:0]	D[17:0],WRX,RDX,CSX,D/CX
0	1	0	1	3-wire 9-bit data serial interface Ⅰ	SCL,SDA,CSX	
0	1	1	0	4-wire 8-bit data serial interface Ⅰ	SCL,SDA,D/CX,CSX	
1	0	0	0	8080 MCU 16-bit bus interface Ⅱ	D[8:1]	D[17:10],D[8:1],WRX,RDX,CSX,D/CX
1	0	0	1	8080 MCU 8-bit bus interface Ⅱ	D[17:10]	D[17:10],WRX,RDX,CSX,D/CX
1	0	1	0	8080 MCU 18-bit bus interface Ⅱ	D[8:1]	D[17:0],WRX,RDX,CSX,D/CX
1	0	1	1	8080 MCU 9-bit bus interface Ⅱ	D[17:10]	D[17:9],WRX,RDX,CSX,D/CX
1	1	0	1	3-wire 9-bit data serial interface Ⅱ	SCL,SDI,SDO, CSX	
1	1	1	0	4-wire 8-bit data serial interface Ⅱ	SCL,SDI,D/CX,SDO, CSX	

4. Absolute Maximum Ratings

The absolute maximum rating is listed on following table. When ILI9341 is used out of the absolute maximum ratings, ILI9341 may be permanently damaged. To use ILI9341 within the following electrical characteristics limitation is strongly recommended for normal operation. If these electrical characteristic conditions are exceeded during normal operation, ILI9341 will malfunction and cause poor reliability.

Item	Symbol	Unit	Value
Supply voltage	VCI	V	-0.3 ~ +4.6
Supply voltage (Logic)	VDDI	V	-0.3 ~ +4.6
Supply voltage (Digital)	VCORE	V	-0.3 ~ +2.0
Driver supply voltage	VGH-VGL	V	-0.3 ~ +32.0
Logic input voltage range	VIN	V	-0.3 ~ VDDI + 0.3
Logic output voltage range	VO	V	-0.3 ~ VDDI + 0.3
Operating temperature	Topr	℃	-40 ~ +85
Storage temperature	Tstg	℃	-55 ~ +110
Note: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.			

5. Electrical Characteristics

Item	Symbol	Unit	Condition	Min.	Typ.	Max.	Note
Power and Operation Voltage							
Analog Operating Voltage	VCI	V	Operating voltage	2.5	2.8	3.3	Note2
Logic Operating Voltage	VDDI	V	I/O supply voltage	1.65	2.8	3.3	Note2
Digital Operating voltage	VCORE	V	Digital supply voltage	-	1.5	-	Note2
Gate Driver High Voltage	VGH	V	-	10.0	-	16.0	Note3
Gate Driver Low Voltage	VGL	V	-	-10.0	-	-5.0	Note3
Driver Supply Voltage	-	V	|VGH-VGL|	15	-	28	Note3
Current consumption during standby mode	I_{ST}	μA	VCI=2.8V , Ta=25 ℃	-	-	100	-
Input and Output							
Logic High Level Input Voltage	VIH	V	-	0.7*VDDI	-	VDDI	Note1,2,3
Logic Low Level Input Voltage	VIL	V	-	VSS	-	0.3*VDDI	Note1,2,3
Logic High Level Output Voltage	VOH	V	IOL=-1.0mA	0.8*VDDI	-	VDDI	Note1,2,3
Logic Low Level Output Voltage	VOL	V	IOL=1.0mA	VSS	-	0.2*VDDI	Note1,2,3
Logic High Level Input Current	IIH	uA	-	-	-	1	Note1,2,3
Logic Low Level input Current	IIL	uA	-	-1	-	-	Note1,2,3
Logic Input Leakage Current	ILEA	uA	VIN=VDDI or VSS	-0.1	-	+0.1	Note1,2,3
VCOM Operation							
VCOM High Voltage	VCOMH	V	Ccom=12nF	2.5	-	5.0	Note3
VCOM Low Voltage	VCOML	V	Ccom=12nF	-2.5	-	0.0	Note3
VCOM Amplitude Voltage	VCOMA	V	|VCOMH-VCOML|	4.0	-	5.5	Note3
Source Driver							
Source Output Range	Vsout	V	-	0.1	-	DDVDH-0.1	Note4
Gamma Reference Voltage	GVDD	V	-	3.0	-	5.0	Note3
Output Deviation Voltage (Source Output channel)	Vdev	mV	Sout>=4.2V Sout<=0.8V	-	-	20	Note4
			4.2V>Sout>0.8V	-	-	15	-
Output Offset Voltage	VOFSET	mV	-	-	-	35	Note7
Booster Operation							
1st Booster (VCIx2) Voltage	DDVDH	V	-	4.95 (Note 5)	-	5.8 (Note 6)	Note3
1st Booster (VCIx2 Drop Voltage	VCIx2 drop	%	loading=1mA	-	-	5	Note3
Liner Range	Vliner	V	-	0.2	-	DDVDH-0.2	

Note 1: VDDI=1.65 to 3.3V, VCI=2.5 to 3.3V, AGND=VSS=0V, Ta=-30 to 70 (to +85 no damage) ℃.

Note2: Please supply digital VDDI voltage equal or less than analog VCI voltage.

Note3: CSX, RDX, WRX, D[17:0], D/CX, RESX, TE, DOTCLK, VSYNC, HSYNC, DE, SDA, SCL, IM3, IM2, IM1, IM0, and Test pins.

Note4: When the measurements are performed with LCD module. Measurement Points are like Note3.

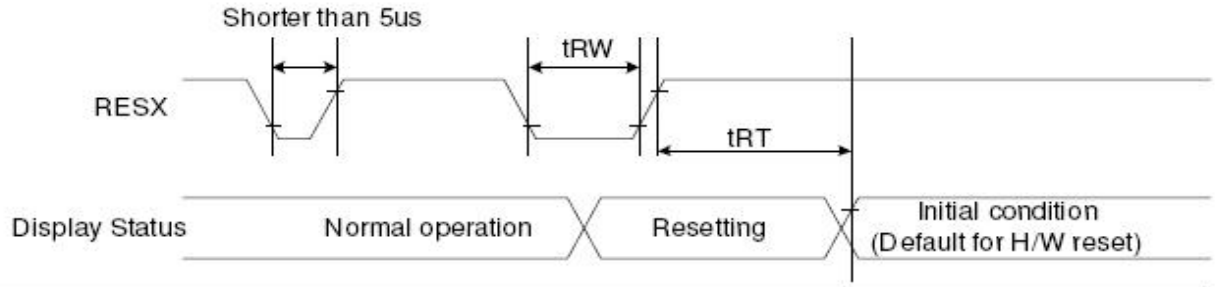
Note5: VCI=2.6V

Note6: VCI=3.3V

Note7: The Max. Value is between with Note 4 measure point and Gamma setting value

6.Timing Characteristics.

6.1 Reset Timing Characteristics.



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

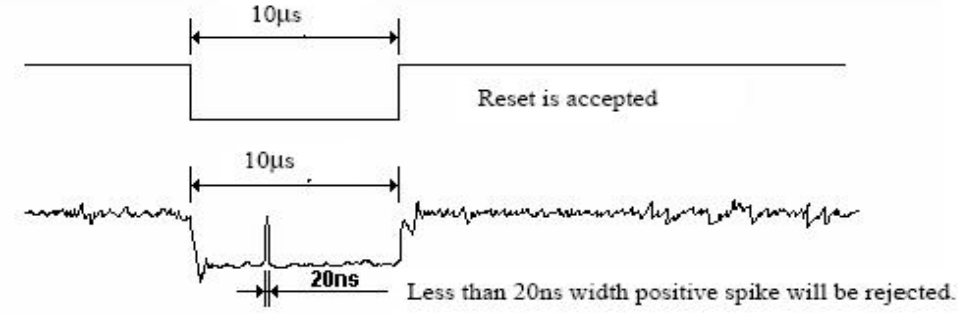
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



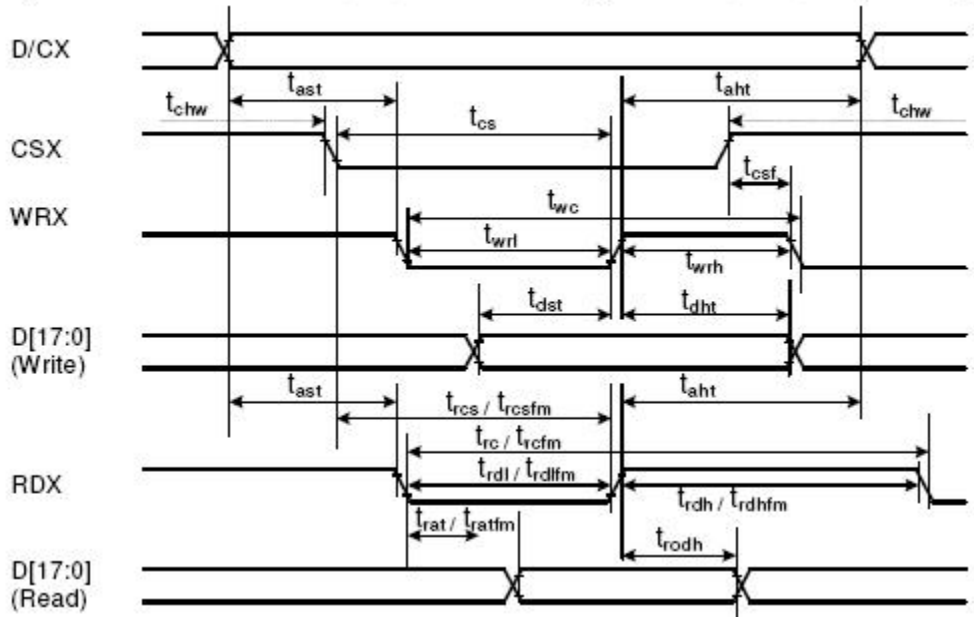
Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

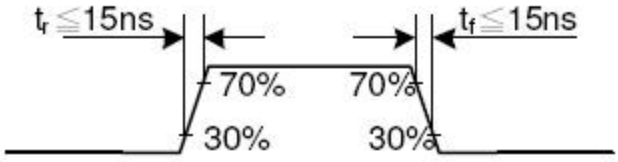
6.2. i80-System Interface Timing Characteristics.

Display Parallel 18/16/9/8-bit Interface Timing Characteristics (8080- I system)

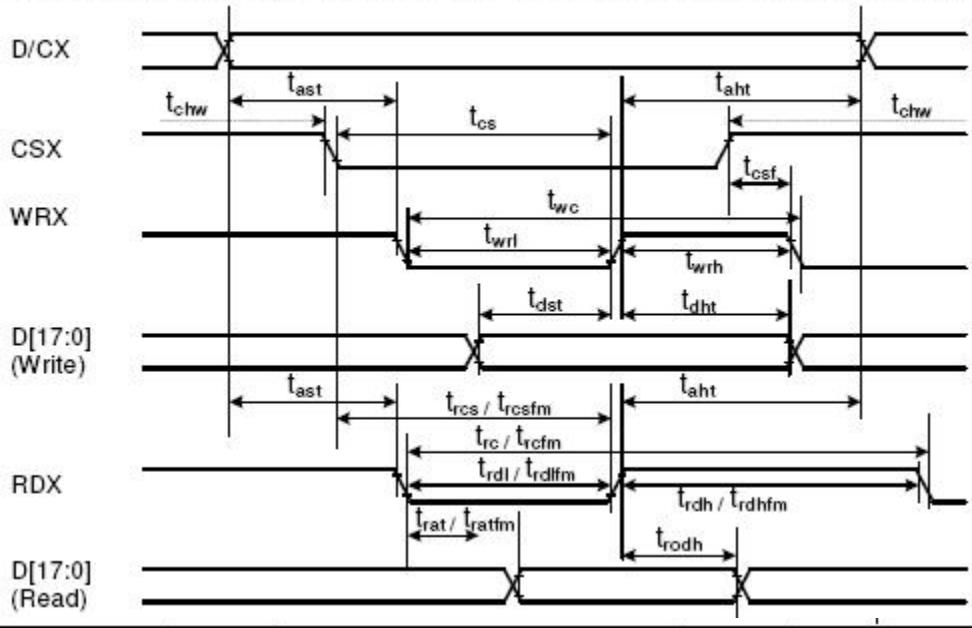


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V

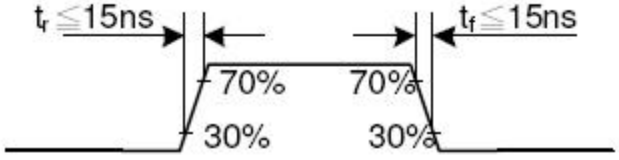


Display Parallel 18/16/9/8-bit Interface Timing Characteristics(8080-Ⅱ system)



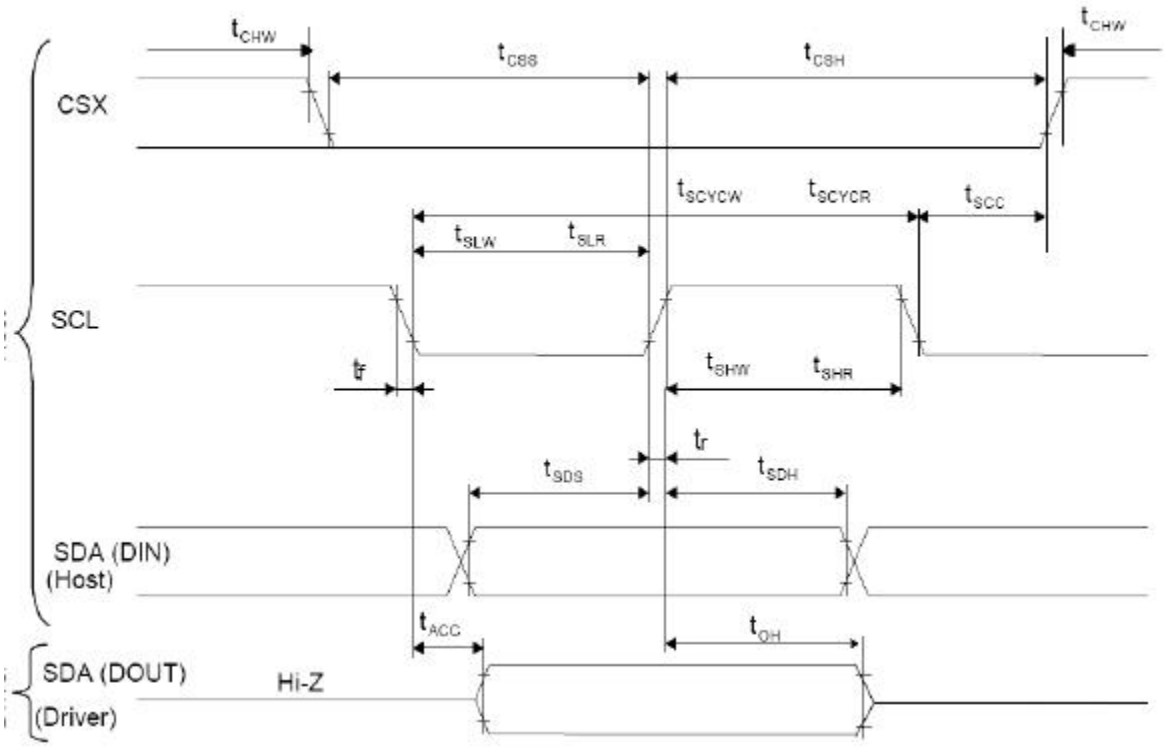
Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
	taht	Address hold time (Write/Read)	0	-	ns	
CSX	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
WRX	twc	Write cycle	66	-	ns	
	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
RDX (FM)	trcfm	Read Cycle (FM)	450	-	ns	
	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
RDX (ID)	trc	Read cycle (ID)	160	-	ns	
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[17:0], D[17:10]&D[8:1], D[17:10], D[17:9]	tdst	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V.



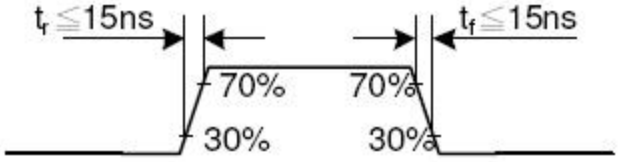
6.3. SPI Interface Timing Characteristics.

Display Serial Interface Timing Characteristics (3-line SPI system)

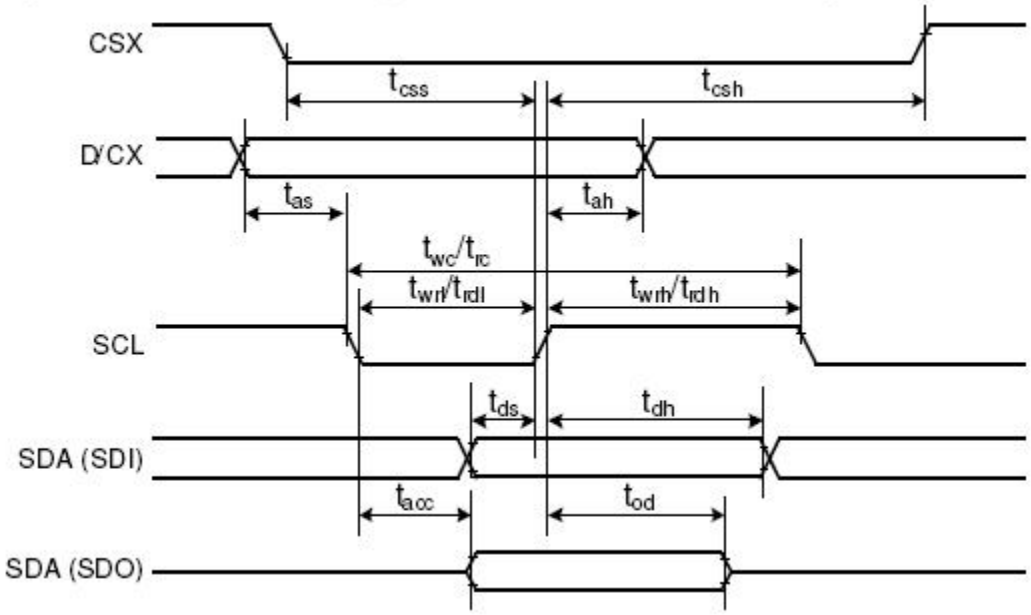


Signal	Symbol	Parameter	min	max	Unit	Description
SCL	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	40	-	ns	
	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI (Input)	tsds	Data setup time (Write)	30	-	ns	
	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	
	toh	Output disable time (Read)	10	50	ns	
CSX	tscc	SCL-CSX	20	-	ns	
	tchw	CSX "H" Pulse Width	40	-	ns	
	tcss	CSX-SCL Time	60	-	ns	
	tcsh		65	-	ns	

Note: Ta = 25 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

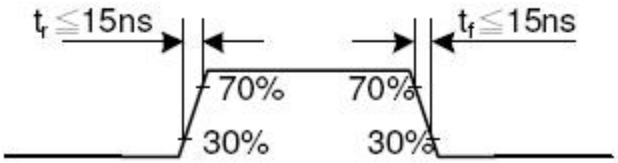


Display Serial Interface Timing Characteristics (4-line SPI system)

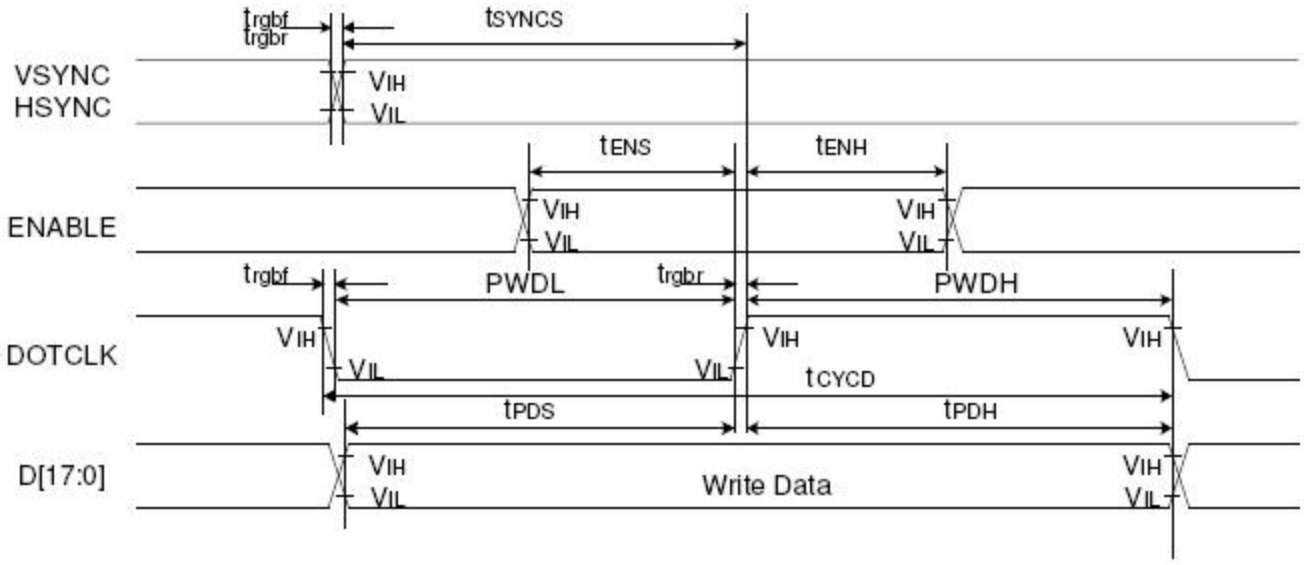


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	40	-	ns	
	tcsh	Chip select hold time (Read)	40	-	ns	
SCL	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
	twrl	SCL "L" pulse width (Write)	40	-	ns	
	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
D/CX	tas	D/CX setup time	10	-		
	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI (Input)	tds	Data setup time (Write)	30	-	ns	
	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO (Output)	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

Note: Ta = 25 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V

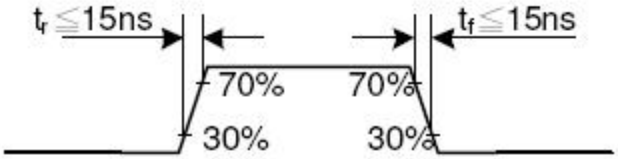


6.4. RGB Interface Timing Characteristics.

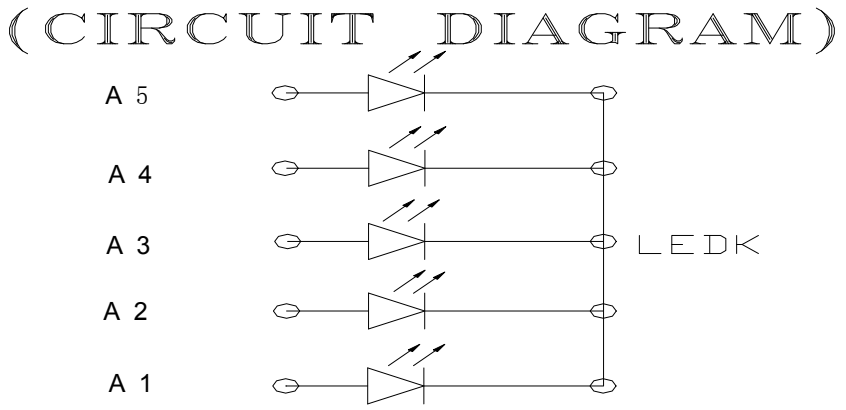


Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{PDS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	15	-	ns	
	PWDL	DOTCLK low-level period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{PDS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level pulse period	15	-	ns	
	PWDL	DOTCLK low-level pulse period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	t_{rgbr} , t_{rgbf}	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, AGND=VSS=0V



7. Backlight Characteristics.



If=75mA(tpye)
Vf=3.2V(tpye)

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition	Note
Supply Voltage	**Vf**	**3.0**	**3.2**	**3.4**	**V**	**If=75 mA**	**-**
Supply Current	**If**	**-**	**75**	**-**	**mA**	**-**	**-**
Reverse Voltage	**Vr**	**-**	**-**	**5**	**V**	**10uA**	
Power dissipation	**Pd**	**-**	**240**	**-**	**mW**	**-**	
Luminous Intensity for LCM		**330**	**330**	**360**	**Cd/m²**	**If=75 mA**	
Uniformity for LCM	**-**	**80**	**-**	**-**	%	**If=75 mA**	
Life Time	**-**	**20000**	**-**	**-**	**Hr**	**If=75 mA**	**-**
Backlight Color	**X**	**0.27**	**0.29**	**0.31**	**-**	**If=75 mA**	
	Y	**0.27**	**0.29**	**0.31**	**-**	**If=75 mA**	

8.Optical Characteristics

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Transmittance (without Polarizer)		T(%)	—	—	18.0	—	—	
Contrast Ratio		CR	Θ=0 Normal viewing angle	400	500	—	—	(1)(2)
Response time	Rising	T_R	—	—	4	8	msec	(1)(3)
	Falling	T_F	—	—	12	24		
Color gamut		S(%)			60		%	
Color chromaticity (CIE1931)	White	W_x		0.283	0.303	0.323		(1)(4) CF glass (C-light)
		Wy		0.305	0.325	0.345		
	Red	Rx		0.606	0.626	0.646		
		Ry		0.314	0.334	0.354		
	Green	Gx		0.257	0.277	0.297		
		Gy		0.529	0.549	0.569		
	Blue	Bx		0.122	0.142	0.162		
		By		0.102	0.122	0.142		
Viewing angle	Hor.	Θ_L	CR>10	35	70	—		
		Θ_R		35	70	—		
	Ver.	Θ_U		35	70	—		
		Θ_D		10	55	—		
Optima View Direction		12 O'clock						(5)

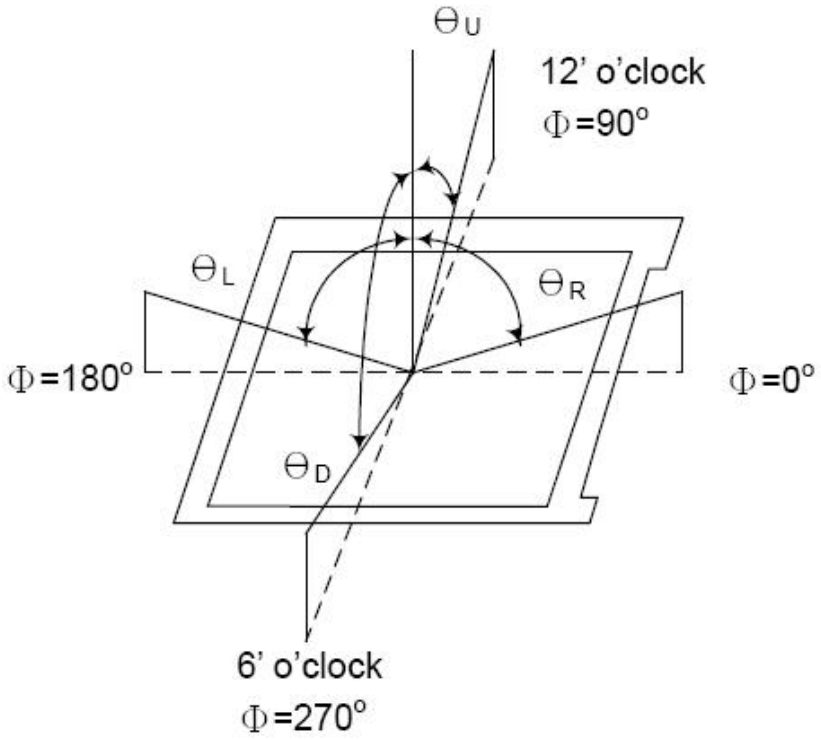
4.2 Measuring Condition

- Measuring surrounding : dark room
- Ambient temperature : 25±2°C
- 15min. warm-up time.

4.3 Measuring Equipment

- FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

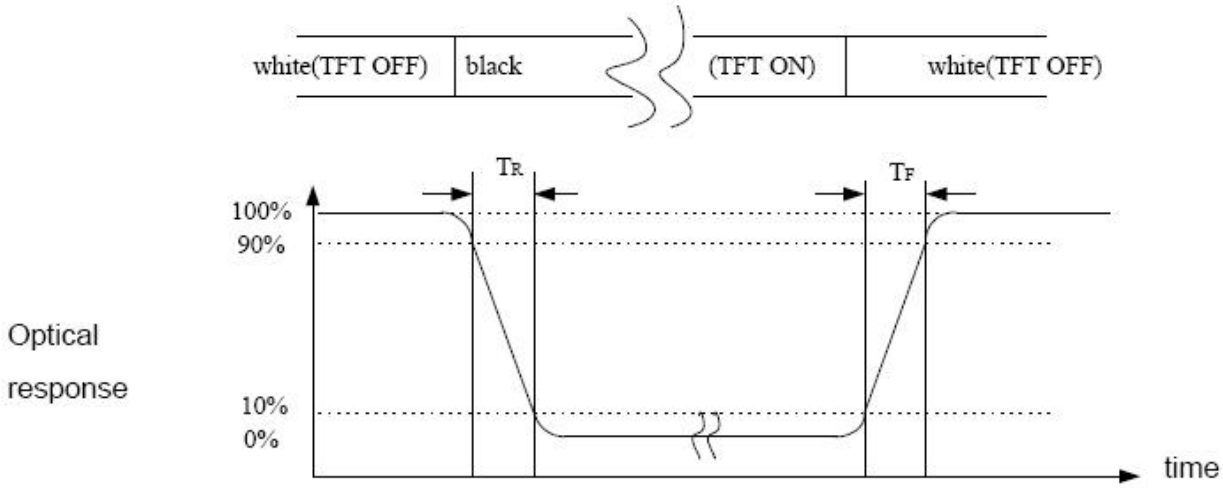
Note (1) Definition of Viewing Angle :



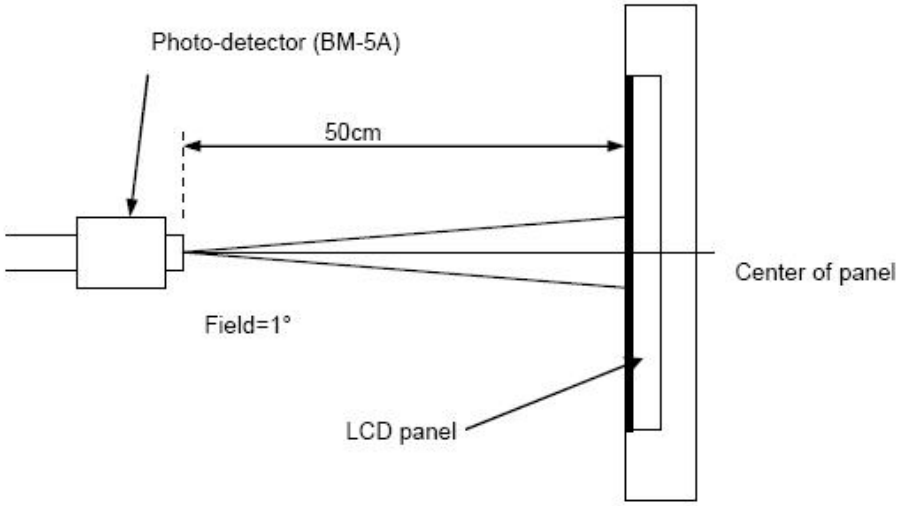
Note (2) Definition of Contrast Ratio(CR) :
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note (3) Definition of Response Time : Sum of T_R and T_F



Note (4) Definition of optical measurement setup



9. RELIABILITY

No.	Test Item	Test Condition	Remark
1	High Temperature Storage	+80℃± 2℃，96 hrs	Note
2	Low Temperature Storage	-30℃± 2℃，96 hrs	Note
3	High Temperature Operation	+70℃± 2℃，96 hrs	Note
4	Low Temperature Operation	+20℃± 2℃，96 hrs	Note
5	High Temperature & High Humidity Storage Test	+50℃± 5℃, 90％R.H, 96 hours	Note
6	Temperature Cycle (non operation)	-30℃ ← +25℃ → +80℃ (30mins ← 5mins →30mins) 10 Cycles	Note
7	Electronic Static Discharge	Air Discharge: 2KV to with 5 times Ambiance: 15℃~35℃,30%~60%R.H Resistance(Rd): 330Ω ±10% Capacitance(Cs + Cd): 150pF±10%	Discharge for each polarity Mode of Operation: Single Discharge, successive discharge at least 1 sec
8	Vibration (Packaged)	Frequency range: 10Hz ~ 55 Hz Amplitude: 1.5mm Direction of X.Y. Z for 3 Hrs in total	
9	Drop Test (Packaged)	Height: 80cm, Time: 1 1 corner, 3 edged, 6 surfaces	

Note : Recovery Time should be 2~4 hours at room temperature (20±8℃) and humidity (below 60% R.H). No abnormalities in functions and appearance

10.INSPECTION CRITERION

10.1 Scope
Display Quality Evaluation
Mechanics Specification

10.2 Sampling Plan
MIL-STD-105E
Unless there is other agreement, the sampling plan for incoming inspection shall follow MIL-STD-105E
Lot size: Quantity per shipment as one lot (different model as different lot).
Sampling type: Normal inspection, single sampling
Sampling level: Level II.

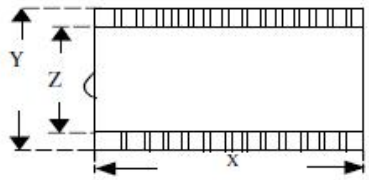
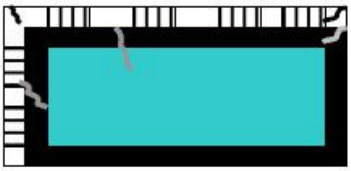
10.3 Acceptable Quality Level

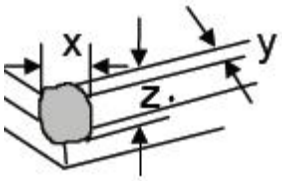
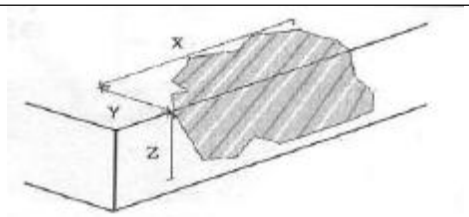
Item	Major	Minor
Appearance	1.0%	1.5%
Electrical	0.65	1.0%

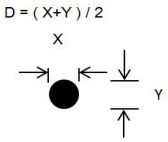
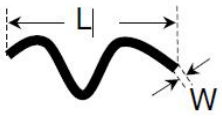
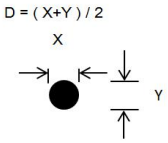
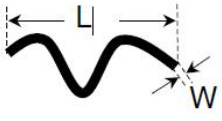
10.3.1 Classification of defects：
10.3.1.1Major defect
Any defect may result in functional failure, or reduce the usability of product for its purpose. For Example：Electrical failure, deformation and etc.
10.3.1.2 Minor defect
The criteria on major or minor judgment will be according with the classification of defects.

10.4 Panel Inspection Condition
10.4.1 Environment:
10.4.2 Room Temperature: 25±5° C.
10.4.3Humidity: 50±20% RH.
Illumination: 300 ~ 700 Lux.
10.4.4 Inspection Distance: 35±5 cm

10.5 TFT Inspection Criteria
10.5.1 Visual inspection criterion in cosmetic / appearance

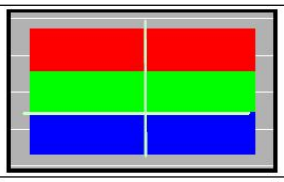
Glass defect			
No	Item	Criteria	Remark
1	Dimension (Minor)	By engineering diagram	
2	Crack (Major)	Extensive crack	

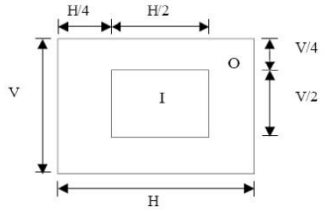
3	Corner (Minor)	X ≤3 mm Y ≤3 mm Z≤ T Ignore	 T: Glass thickness Z: Thickness X: Length Y: Width
4	Side (Minor)	X ≤5mm Y ≤3 mm Z≤ T Ignore	 T: Glass thickness Z: Thickness X: Length Y: Width

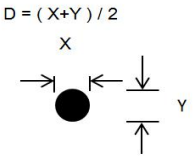
TFT defect in appearance			
No	Item	Criteria	Remark
1	Foreign Spot (Minor) Including: Black spot, White spot Pin hole Foreign particle	D≤0.15mm，Ignore 0.15mm<D≤0.3mm，N≤3 0.3mm<D，N=0 Distance≥5mm Ignore if out of Area AA	D =(X+Y)/2, X: Length, Y: Width 
2	Foreign Line(Minor) Including: Black line White line Bright line	W≤0.03mm，Ignore 0.03mm<W≤0.05mm, L≤4mm, N≤3 0.05mm<W≤0.08mm, L≤4mm, N≤1 W>0.08mm, N=0 Ignore if out of Area AA	L: Length, W: Width 
3	Polarizer Dent/Air Bubble (Minor)	D≤0.2mm，Ignore 0.2mm<D≤0.3mm，N≤3 0.3mm<D≤0.5mm，N≤1 D>0.50mm, N=0 Distance≥5mm	D =(X+Y)/2, X: Length, Y: Width 
4	Polarizer Scratches (Minor)	W≤0.03mm，Ignore 0.03mm<W≤0.05mm, L≤4mm, N≤3 0.05mm<W≤0.08mm, L≤4mm, N≤1 W>0.08mm, N=0 Ignore if out of Area AA	L: Length, W: Width 

Other defects			
No	Item	Criteria	Remark
1	FPC (Minor)	Any crack or breakage which effect the function are not allowed Disregard if the dirty removed	
2	Backlight (Minor)	Power up is allowed. Breaking off is not allowed. The scratch which may causes a problem in practical use is not allowed	
3	Bezel (Minor)	Erasable dirt is ignore	

10.5.2 Visual inspection criterion in electrical display

Glass defect			
No	Item	Criteria	Remark
1	No display (Major) Abnormally Short circuit	Not allowed	
2	Missing line (Major)	Not allowed	
3	Darker or lighter line (Major)	Not allowed	
4	Weak line (Minor)	By limit sample	

<table>
<tr><td colspan="4">Display Inspection</td></tr>
<tr><td>No</td><td>Item</td><td>Criteria</td><td>Remark</td></tr>
<tr><td>1</td><td>Bright / Dark dot</td><td>
<table>
<tr><td>Items</td><td>Area I</td><td>Area O</td><td>Total</td></tr>
<tr><td>Bright</td><td>1</td><td>1</td><td>1</td></tr>
<tr><td>Dark</td><td>1</td><td>3</td><td>3</td></tr>
<tr><td>Bright & Dark</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>2 adjacent dots</td><td>0</td><td>0</td><td>0</td></tr>
<tr><td colspan="4">Minimum Distance ≥ 5mm</td></tr>
</table>
</td><td> 

1.1sub-pixel: 1R or 1G or 1B
2.Point defect area≥ 1/2 sub pixel</td></tr>
<tr><td>2</td><td>Tiny bright dot</td><td>Visible through 6% ND filter
D≤0.15mm，Ignore
0.15mm<D≤0.3mm，N≤3
0.3mm<D≤0.35mm，N≤1
D>0.35mm, N=0
Distance≥5mm
Ignore if out of Area AA</td><td>D =(X+Y)/2,
X: Length, Y: Width
 
</td></tr>
<tr><td>4</td><td>Mura/Waving/ Hot spot</td><td>Not visible through 6% ND filter in 50% gray or judge by limit sample if necessary</td><td></td></tr>
</table>

* Note:
1. Defect which is on the Black Matrix (outside of active area) are not considered as a defect.
2. If any specific defect is not included in the above defect table, this defect should be judged by Formike.
3. W：Width, L：Length D：Average Diameter N: Count.

■ PRECAUTIONS FOR USING LCD MODULES

Handing Precautions

(1) The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.

(2) If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.

(3) Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).

(4) The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming is contacting with room temperature air.

(5) If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents

- Isopropyl alcohol
- Ethyl alcohol

Do not scrub hard to avoid damaging the display surface.

(6) Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.

- Water
- Ketone
- Aromatic solvents

Wipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contacting oil and fats.

(7) Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets, moisture condensation or a current flow in a high-humidity environment.

(8) Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.

(9) Do not attempt to disassemble or process the LCD module.

(10) NC terminal should be open. Do not connect anything.

(11) If the logic circuit power is off, do not apply the input signals.

(12) Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

- Before remove LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.
- Tools required for assembling, such as soldering irons, must be properly grounded. make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.
- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dried. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential
- The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated

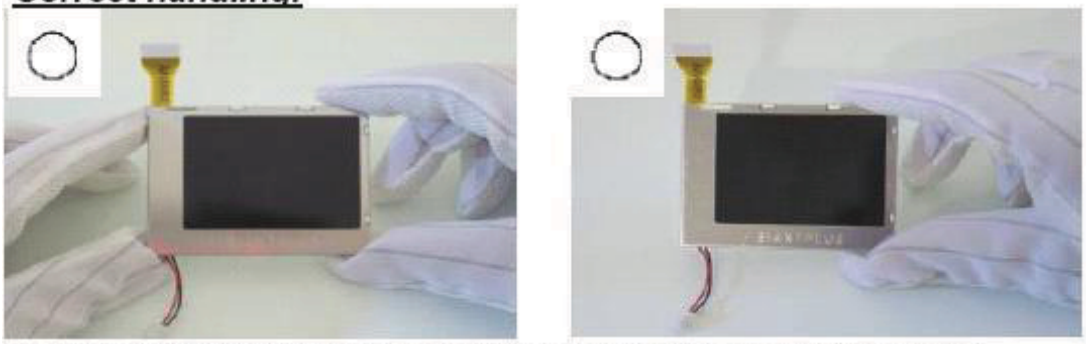
（13）Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- Do not alter, modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist LCM.

Handling precaution for LCM

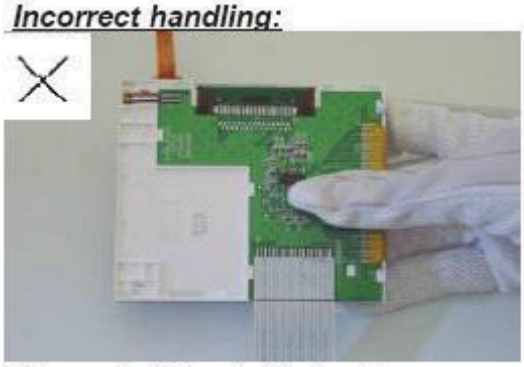
LCM is easy to be damaged.
Please note below and be careful for handling!

Correct handling:

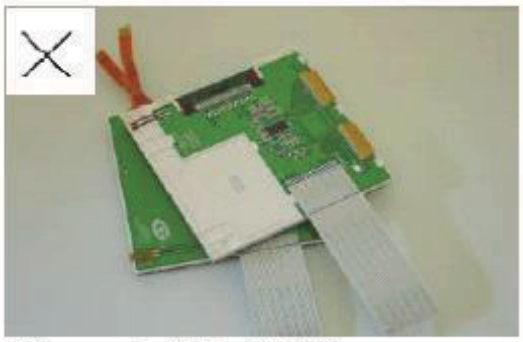


As above picture, please handle with anti-static gloves around LCM edges.

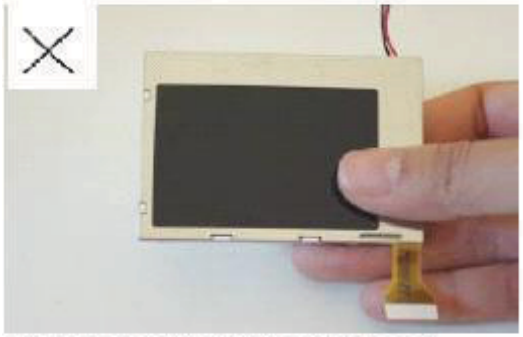
Incorrect handling:



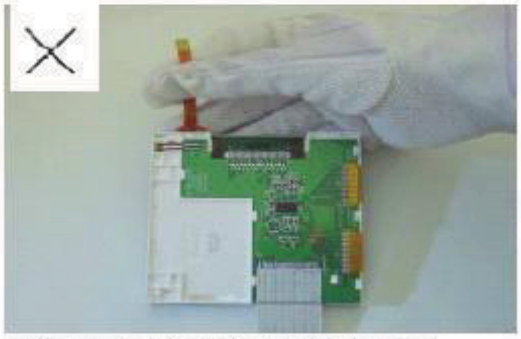
Please don't touch IC directly.



Please don't stack LCM.



Please don't hold the surface of panel.

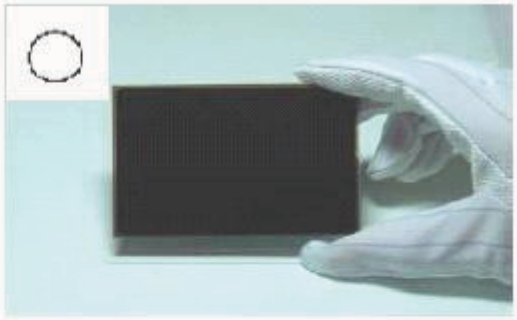


Please don't stretch interface of output, such as FPC cable.

Handling precaution for LCD

LCD is easy to be damaged.
Please note below and be careful for handling!

Correct handling:

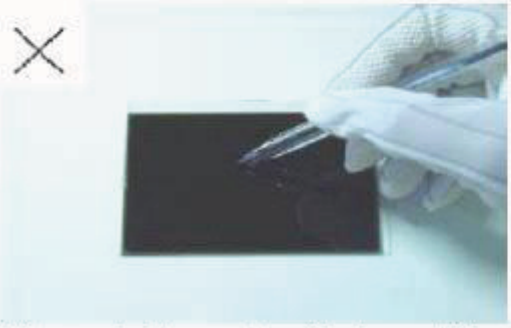


As above photo, please handle with anti-static gloves around LCD edges.

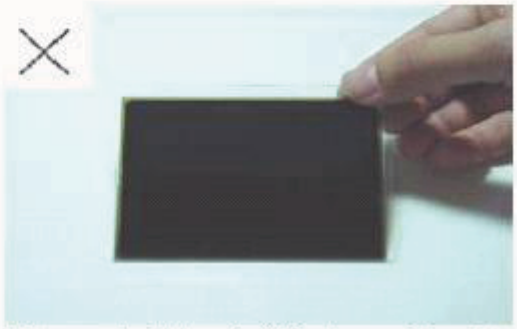
Incorrect handling:

Please don't stack the LCDS.

Please don't hold the surface of LCD.



Please don't operate with sharp stick such as pens.



Please don't touch ITO glass without anti-static gloves.

Storage Precautions

When storing the LCD modules, the following precaution is necessary.

(1) Store them in a sealed polyethylene bag. If properly sealed, there is no need for the dessicant.

(2) Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.

(3) The polarizer surface should not come in contact with any other objects. (We advise you to store them in the anti-static electricity container in which they were shipped.

Others

Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

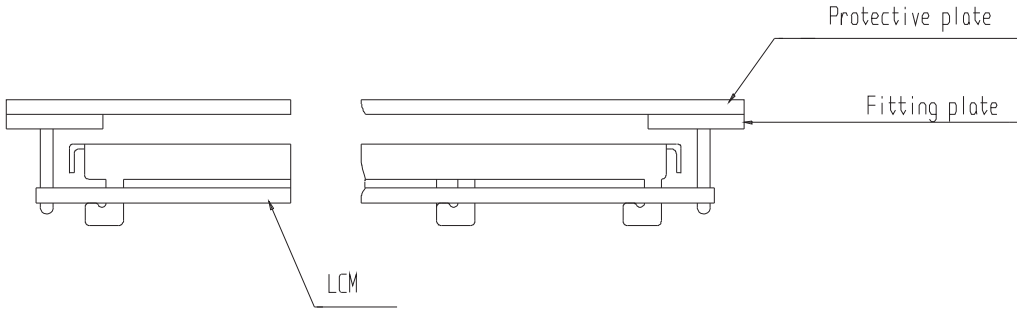
- Exposed area of the printed circuit board.
-Terminal electrode sections.

USING LCD MODULES

Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

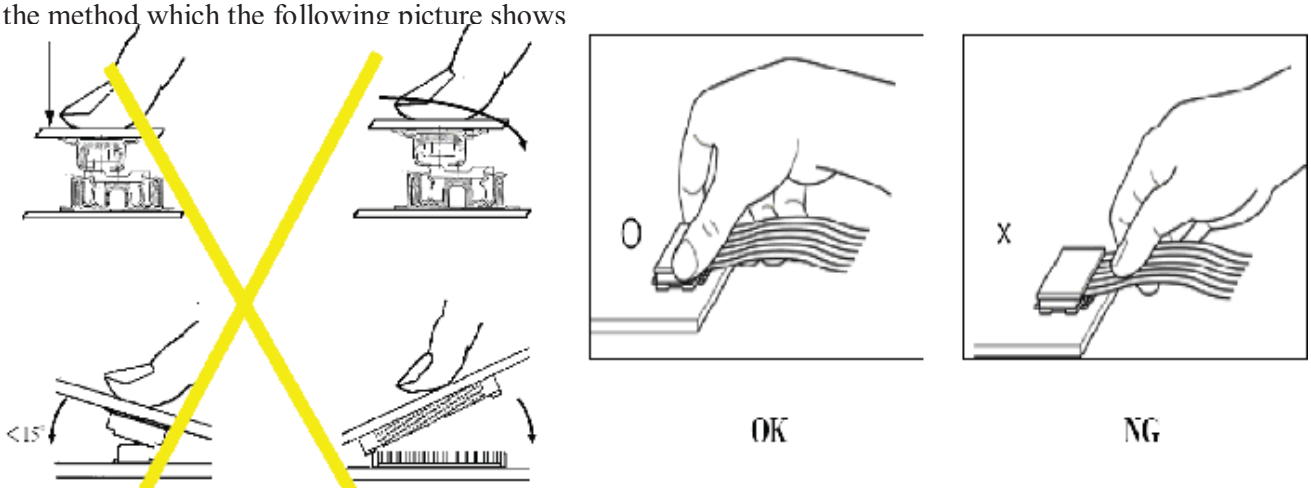
(1) Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



(2) When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be ±0.1mm.

Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position,don't assemble or assemble like the method which the following picture shows



Precaution for soldering to the LCM

	Hand soldering	Machine drag soldering	Machine press soldering
No ROHS product	290°C ~350°C. Time : 3-5S.	330°C ~350°C. Speed : 4-8 mm/s.	300°C ~330°C. Time : 3-6S. Press: 0.8~1.2Mpa
ROHS product	340°C ~370°C. Time : 3-5S.	350°C ~370°C. Time : 4-8 mm/s.	330°C ~360°C. Time : 3-6S. Press: 0.8~1.2Mpa

(1) If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters.

(2) When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

(3) When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

Precautions for Operation

(1) Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.

(2) It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.

(3) Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, Which will come back in the specified operating temperature.

(4) If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

(5) A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature,50%RH or less is required.

(6) Input each signal after the positive/negative voltage becomes stable.

(7) Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity.

Safety

(1) It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol, which should later be burned.

(2) If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water.

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Limited Warranty

Unless agreed otherwise between Display Future Ltd and customer, Display Future will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned within 90 days of the shipment. Confirmation of such date shall be based on data code on the product.
The warranty liability of Display Future limited to repair and/or replacement on the terms set forth above. Display Future will not be responsible for any subsequent or consequential events.

Return LCM under warranty

No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

- Broken LCD glass.
- PCB eyelet is damaged or modified.
- PCB conductors damaged.
- Circuit modified in any way, including addition of components.
- PCB tampered with by grinding, engraving or painting varnish.
- Soldering to or modifying the bezel in any manner.

Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

■ PRIOR CONSULT MATTER

1.①For Display Future standard products, we keep the right to change material and processes for improving the product, without notice to our customers.
②For OEM products, if any change is needed, which may affect the product property, we will consult with our customer in advance.
2. If you have special requirement about reliability condition, please let us know before you start the test on our samples.